



For board-to-board

Narrow pitch connectors (0.5mm pitch)

FEATURES

 Low profile mated height of 1.2 mm and 0.5 mm pitch contributes to device miniaturization.
 Strong resistance to adverse environments! Utilizes
 TDUGH CONTRET construction for high contact reliability.
 Simple lock structure provides

tactile feedback to ensure excellent mating/unmating operation feel.



4. Effective mating length 0.3 mm



P5KL Series

APPLICATIONS

7

G

Digital devices, such as digital still cameras and digital video cameras.

AXK 3 5L: Narrow Pitch Connector P5KL (0.5 mm pitch) Socket 6L: Narrow Pitch Connector P5KL (0.5 mm pitch) Header Number of pins (2 digits) Mated height <Socket> 3: For mated height 1.2 mm <Header> 3: For mated height 1.2 mm Functions 3: With positioning bosses 4: Without positioning bosses

Surface treatment (Contact portion / Terminal portion) 7: Ni plating on base, Au plating on surface (for Ni barrier available)

ORDERING INFORMATION

Packing

G: 3,000 pieces embossed tape and plastic reel x 2 (for Ni barrier available)

AXK(5/6)L

PRODUCT TYPES

		Part	No.	Packing quantity	
Mated height	No. of pins	Socket	Header	Inner carton	Outer carton
		TDUGH CDNTRCT	TDUGH CONTRET	(1-reel)	
	10	AXK5L10347G	AXK6L10347G		
	12 AXK5L12347G 20 AXK5L20347G 24 AXK5L24347G 30 AXK5L30347G 34 AXK5L34347G 40 AXK5L40347G 46 AXK5L46347G	AXK6L12347G		6,000 pieces	
		AXK6L20347G			
		AXK6L24347G			
(!) 1.2 mm		AXK6L30347G	3,000 pieces		
1.2 1111		AXK6L34347G			
		AXK6L40347G			
		AXK6L46347G			
	50	AXK5L50347G	AXK6L50347G		
	60	AXK5L60347G	AXK6L60347G		

Notes: 1. Regarding ordering units: During production, Please make orders in 1-reel units. Samples for mounting confirmation: Please consult us. Samples: Small lot orders are possible. Please consult us.

2. The standard type comes without positioning bosses. Connectors with positioning bosses are available for on-demand production.

For this type of connector, 9th digit of the part no. changes from 4 to 3. e.g. 10 pin contacts for sockets: AXK5L10337G

SPECIFICATIONS

1. Characteristics

Item		Specifications	Conditions			
Rated current		0.5A/pin contact (Max. 10 A at total pin contacts)				
Electrical characteristics	Rated voltage	60V AC/DC				
	Breakdown voltage	150V AC for 1 minute	Detection current: 1mA			
	Insulation resistance	Min. 1,000M Ω (initial)	Using 500V DC megger			
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.			
	Composite insertion force	Max. 0.981N {100gf}/pin contacts \times pin contacts (initial)				
Mechanical	Composite removal force	Min. 0.0588N {6gf}/pin contacts × pin contacts				
characteristics	Holding force of terminal securing section	Min. 0.981N {100gf}/pin contact	Measuring the maximum force. As the contact is axially pull out.			
	Ambient temperature	–55°C to +85°C	No freezing at low temperatures			
	Soldering heat resistance	Max. peak temperature of 260°C (on the surface of the PC board around the connector terminals)	Infrared reflow soldering			
	Soluening heat resistance	300°C within 5 seconds 350°C within 3 seconds	Soldering iron			
	Storage temperature	−55°C to +85°C (product only) −40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.			
			Conformed to MIL-STD-202F, method 107G			
Environmental characteristics	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Order Temperature (°C) Time (minutes) 1 -55_3 30 2 \$ Max. 5 3 85*3 30 4 \$ Max. 5 -55_3 Under the second secon			
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩBath temperature 40±2°C, humidity 90 to 95% R.H.				
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Bath temperature 35±2°C, saltwarter concentration 5±1%			
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90m Ω	Bath temperature $40\pm2^{\circ}C$, gas concentration 3 ± 1 ppm, humidity 75 to 80% R.H.			
Lifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/hours			
Unit weight		20 pin contacts; Socket: 0.05g; Header: 0.02g				

2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	Heat-resistant resin (UL94V-0)	_
Contact/Post		Contact portion: Ni plating on base, Au plating on surface Terminal portion: Ni plating on base, Au plating on surface (Except for thick of terminal) The section close to the soldering portion has a nickel barrier. (The nickel base is exposed.)

DIMENSIONS

Interested in CAD data? You can obtain CAD data for all products with a CAD Data mark from your local Panasonic Electric Works representative.

(Unit: mm)

AXK(5/6)L





Dimension table (mm)				
No. of contacts	А	В		
10	5.50	2.00		
12	6.00	2.50		
20	8.00	4.50		
24	9.00	5.50		
30	10.50	7.00		
34	11.50	8.00		
40	13.00	9.50		
46	14.50	11.00		
50	15.50	12.00		
60	18.00	14.50		

General tolerance: ± 0.2

(0.65)

3.30

(0.65)

Terminal coplanarity

0.10

• Header (Mated height: 1.2mm)





No. of contacts	А	В
10	3.90	2.00
12	4.40	2.50
20	6.40	4.50
24	7.40	5.50
30	8.90	7.00
34	9.90	8.00
40	11.40	9.50
46	12.90	11.00
50	13.90	12.00
60	16.40	14.50

• Socket and header are mated



General tolerance: ±0.2

EMBOSSED TAPE DIMENSIONS (unit: mm, Common for respective contact type, socket and header)

• Tape dimensions (Conforming to JIS C 0806-1990. However, some tapes have mounting hole pitches that do not comply with the standard.)



• Plastic reel dimensions (Conforming to EIAJ ET-7200B)



Dimension table (mm)

Suffix: G (1 reel, 3,000 pieces embossed tape: Plastic reel package)

Mated height	No. of pins	Type of taping	А	В	С	D	Quantity per reel
	10 to 18	Tape I	16.0	—	7.5	17.4	3,000 pcs.
Socket and header are common: 1.2mm	20 to 50	Tape I	24.0	—	11.5	25.4	3,000 pcs.
1.211111	60	Tape II	32.0	28.4	14.2	33.4	3,000 pcs.

Connector orientation with respect to direction of progress of embossed tape



NOTES

1. As shown below, excess force during insertion may result in damage to the connector or removal of the solder. Also, to prevent connector damage plese confirm the correct position before mating connectors.



than 0.03 mm in relation to the overall length of the connector.



3. Recommended PC board and metal mask patterns

Connectors are mounted with high pitch density, intervals of 0.35 mm, 0.4 mm or 0.5 mm.

In order to reduce solder bridges and other issues make sure the proper levels of solder is used.

The figures to the right are recommended metal mask patterns. Please use them as a reference.



Recommended PC board pattern (TOP VIEW)



Recommended metal mask pattern Metal mask thickness: 150 μm (Terminal portion opening area ratio: 57%)



Recommended metal mask pattern Metal mask thickness: 120 µm (Terminal portion opening area ratio: 70%)



Notes: 1. See the dimension table on page 3 for more information on the B dimension of the socket and header.

- 2. The socket C dimension is the B dimension
 - in the dimensions table with 0.8 added.

Header

Recommended PC board pattern (TOP VIEW)



Recommended metal mask pattern Metal mask thickness: 150 um (Terminal portion opening area ratio: 56%)



Recommended metal mask pattern Metal mask thickness: 120 μ m (Terminal portion opening area ratio: 70%)



For Cautions for Use, see Connector Technical Information. For other details, please verify with the product specification sheets.

